

ON Semiconductor				10/16/2019	
Base Part		BCX70G	HF	Pb-free	
Orderable Part		BCX70G	Total weight (mg)		8.706
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight	
Die	0.048	Silicon (Si)	7440-21-3	100	
Lead Frame	2.371	Silver (Ag)	7440-22-4	0.33741038	
		Manganese (Mn)	7439-96-5	0.80134964	
		Silicon (Si)	7440-21-3	0.29523408	
		Nickel (Ni)	7440-02-0	41.96541544	
Mold Compound-Black	6.061	Iron (Fe)	7439-89-6	56.60059047	
		Ortho Cresol Novolac Resin	29690-82-2	19.96370236	
		Carbon Black (C)	1333-86-4	1.00643458	
Plating	0.206	Fused Silica (SiO2)	60676-86-0	79.02986306	
		Tin (Sn)	7440-31-5	100	
Wire Bond - Au	0.02	Gold (Au)	7440-57-5	100	
<p>Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p>http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</p>					